

PXP400-100QS

100 V, P-channel Trench MOSFET

7 May 2020

Product data sheet

1. General description

P-channel enhancement mode Field-Effect Transistor (FET) in an MLPAK33 (SOT8002-2) Surface-Mounted Device (SMD) plastic package using Trench MOSFET technology.

2. Features and benefits

- Trench MOSFET technology
- MLPAK33 package (3.3 x 3.3 mm footprint)
- Low thermal resistance
- Low 0.8 mm profile

3. Applications

- Active clamp circuits

4. Quick reference data

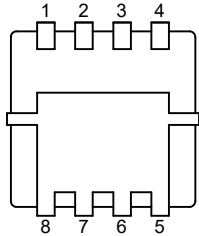
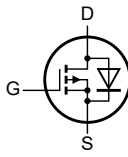
Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{DS}	drain-source voltage	$T_j = 25\text{ °C}$	-	-	-100	V
V_{GS}	gate-source voltage		-20	-	20	V
I_D	drain current	$V_{GS} = -10\text{ V}; T_{amb} = 25\text{ °C}$	[1]	-	-1.4	A
Static characteristics						
R_{DSon}	drain-source on-state resistance	$V_{GS} = -10\text{ V}; I_D = -1.4\text{ A}; T_j = 25\text{ °C}$	-	275	400	mΩ

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and mounting pad for drain 6 cm².

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	S	source	 <p>MLPAK33 (SOT8002-2)</p>	 <p>017aaa094</p>
2	S	source		
3	S	source		
4	G	gate		
5	D	drain		
6	D	drain		
7	D	drain		
8	D	drain		

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PXP400-100QS	MLPAK33	plastic thermal enhanced surface mounted package; mini leads; 8 terminals; pitch 0.65 mm; 3.3 x 3.3 x 0.8 mm body	SOT8002-2

7. Marking

Table 4. Marking codes

Type number	Marking code
PXP400-100QS	8AL

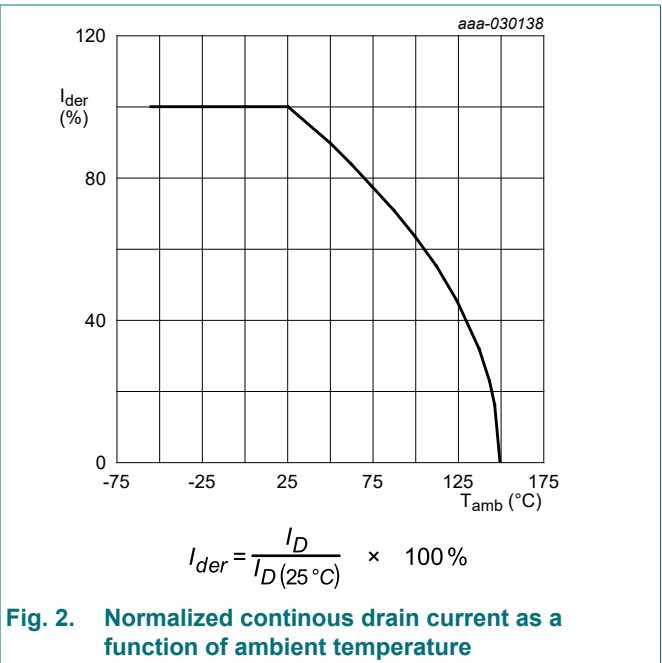
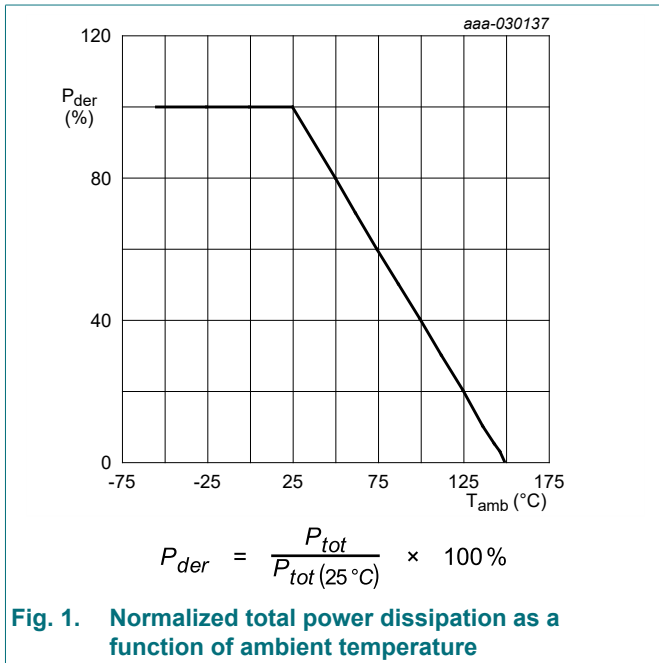
8. Limiting values

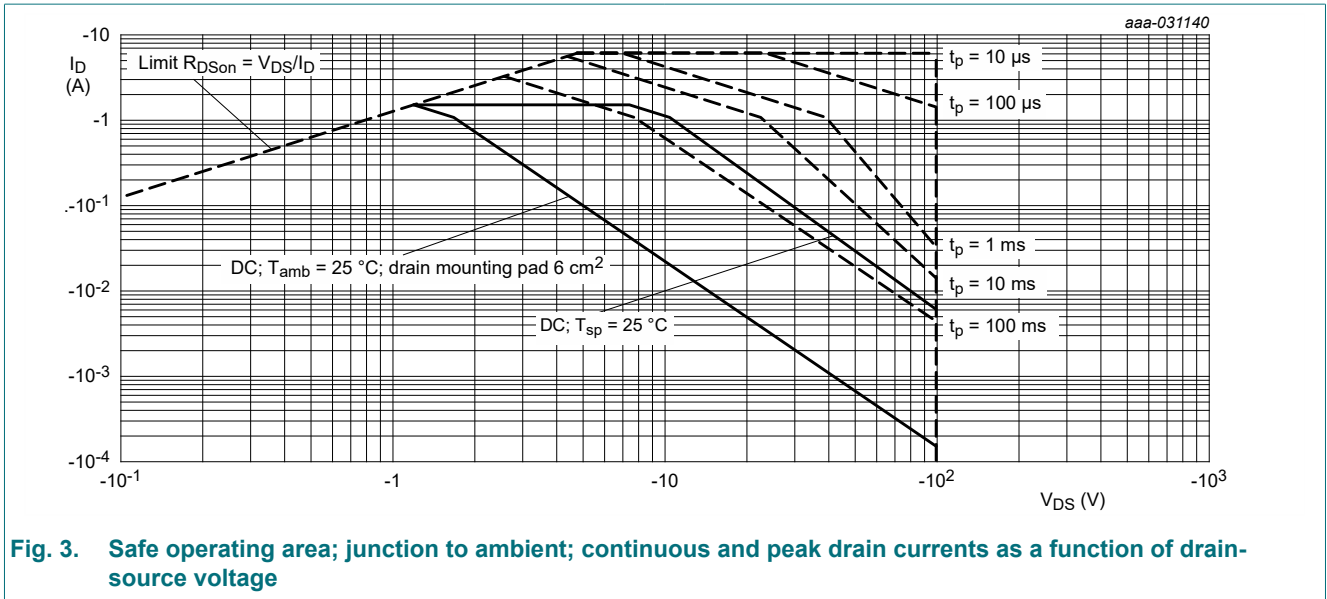
Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V _{DS}	drain-source voltage	T _j = 25 °C		-	-100	V
V _{GS}	gate-source voltage			-20	20	V
I _D	drain current	V _{GS} = -10 V; T _{amb} = 25 °C	[1]	-	-1.4	A
		V _{GS} = -10 V; T _{amb} = 100 °C	[1]	-	-0.9	A
		V _{GS} = -10 V; T _{sp} = 25 °C		-	-3.5	A
I _{DM}	peak drain current	T _{amb} = 25 °C; single pulse; t _p ≤ 10 μs		-	-6	A
P _{tot}	total power dissipation	T _{amb} = 25 °C	[1]	-	1.7	W
		T _{sp} = 25 °C		-	10.4	W
T _j	junction temperature			-55	150	°C
T _{amb}	ambient temperature			-55	150	°C
T _{stg}	storage temperature			-65	150	°C
Source-drain diode						
I _S	source current	T _{amb} = 25 °C	[1]	-	-1.4	A
Avalanche ruggedness						
E _{DS(AL)S}	non-repetitive drain-source avalanche energy	T _{j(initial)} = 25 °C; I _D = -0.58 A; DUT in avalanche (unclamped)		-	28	mJ

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and mounting pad for drain 6 cm².





9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]	-	155	195	K/W
			[2]	-	60	75	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point			-	10	12	K/W

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and mounting pad for drain 6 cm².

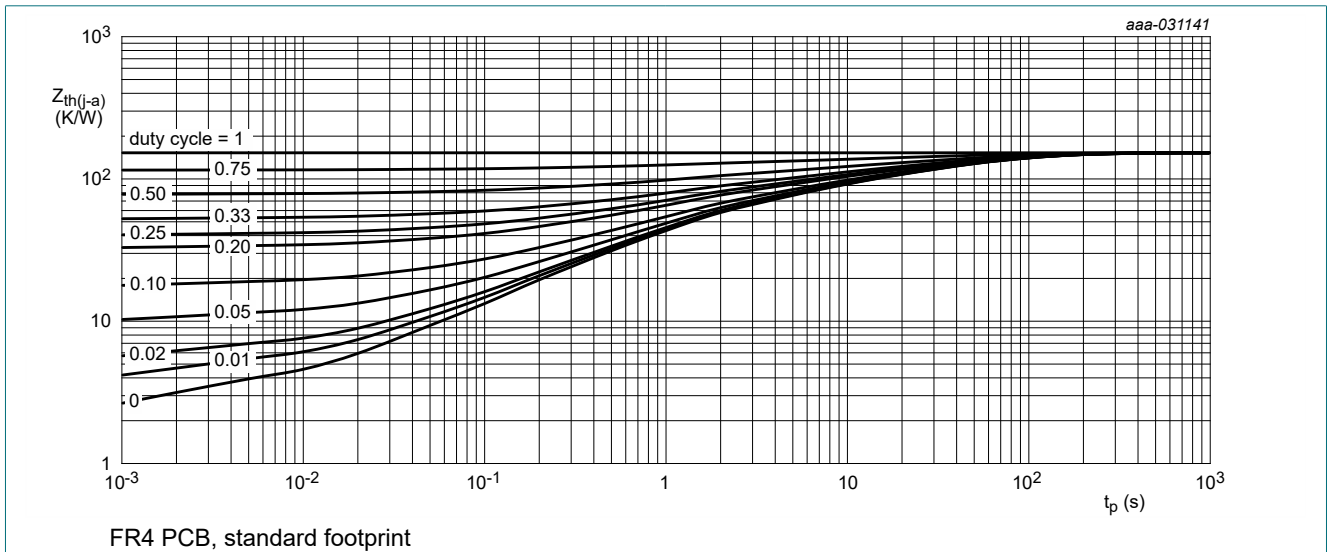


Fig. 4. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

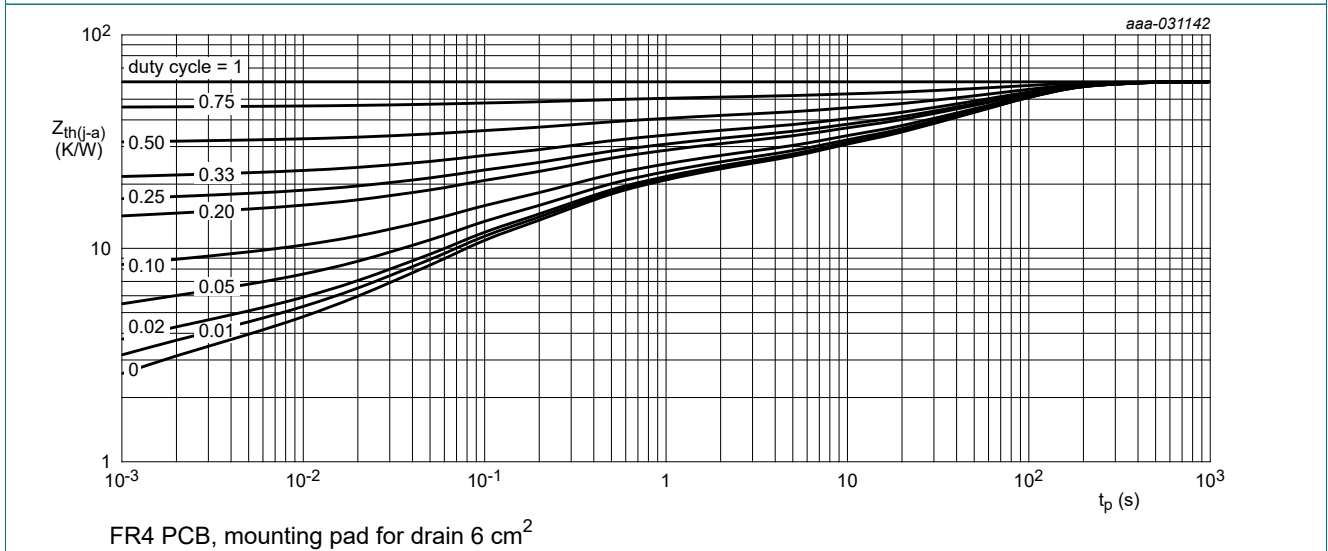


Fig. 5. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
$V_{(BR)DSS}$	drain-source breakdown voltage	$I_D = -250 \mu\text{A}; V_{GS} = 0 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$	-100	-	-	V
V_{GSth}	gate-source threshold voltage	$I_D = -250 \mu\text{A}; V_{DS} = V_{GS}; T_j = 25 \text{ }^\circ\text{C}$	-2	-3	-4	V
I_{DSS}	drain leakage current	$V_{GS} = 0 \text{ V}; V_{DS} = -100 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$	-	-	-1	μA
I_{GSS}	gate leakage current	$V_{GS} = -20 \text{ V}; V_{DS} = 0 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$	-	-	-100	nA
		$V_{GS} = 20 \text{ V}; V_{DS} = 0 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$	-	-	100	nA
R_{DSon}	drain-source on-state resistance	$V_{GS} = -10 \text{ V}; I_D = -1.4 \text{ A}; T_j = 25 \text{ }^\circ\text{C}$	-	275	400	m Ω
		$V_{GS} = -10 \text{ V}; I_D = -1.4 \text{ A}; T_j = 150 \text{ }^\circ\text{C}$	-	580	844	m Ω
		$V_{GS} = -6 \text{ V}; I_D = -1.1 \text{ A}; T_j = 25 \text{ }^\circ\text{C}$	-	290	600	m Ω
g_{fs}	forward transconductance	$V_{DS} = -10 \text{ V}; I_D = -1.4 \text{ A}; T_j = 25 \text{ }^\circ\text{C}$	-	3.9	-	S
R_G	gate resistance	$f = 1 \text{ MHz}$	-	12	-	Ω
Dynamic characteristics						
$Q_{G(tot)}$	total gate charge	$V_{DS} = -50 \text{ V}; I_D = -1.4 \text{ A}; V_{GS} = -10 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$	-	10.1	15.2	nC
		$V_{DS} = -50 \text{ V}; I_D = -1.1 \text{ A}; V_{GS} = -6 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$	-	6.4	9.6	nC
Q_{GS}	gate-source charge	$T_j = 25 \text{ }^\circ\text{C}$	-	1.9	-	nC
Q_{GD}	gate-drain charge		-	2.6	-	nC
C_{iss}	input capacitance	$V_{DS} = -50 \text{ V}; f = 1 \text{ MHz}; V_{GS} = 0 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$	-	544	-	pF
C_{oss}	output capacitance		-	25	-	pF
C_{rss}	reverse transfer capacitance		-	15	-	pF
$t_{d(on)}$	turn-on delay time	$V_{DS} = -50 \text{ V}; I_D = -1.1 \text{ A}; V_{GS} = -4.5 \text{ V}; R_{G(ext)} = 5 \text{ } \Omega; T_j = 25 \text{ }^\circ\text{C}$	-	12	-	ns
t_r	rise time		-	36	-	ns
$t_{d(off)}$	turn-off delay time		-	9	-	ns
t_f	fall time		-	14	-	ns
Source-drain diode						
V_{SD}	source-drain voltage	$I_S = -1.4 \text{ A}; V_{GS} = 0 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$	-	-0.8	-1.2	V
t_{rr}	reverse recovery time	$I_S = -1.4 \text{ A}; di_S/dt = -100 \text{ A}/\mu\text{s}; V_{GS} = -4.5 \text{ V}; V_{DS} = -40 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$	-	27	-	ns
Q_r	recovered charge		-	32	-	nC

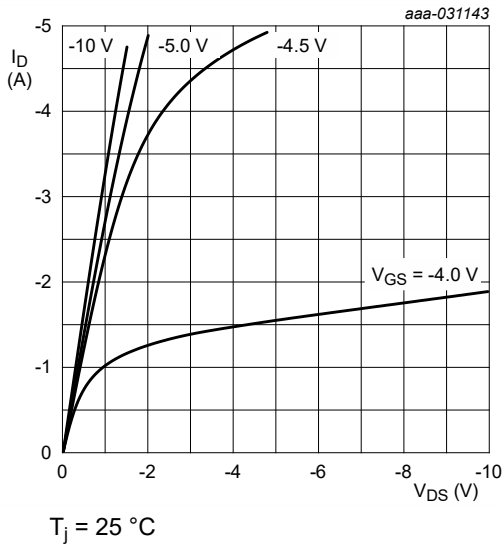


Fig. 6. Output characteristics: drain current as a function of drain-source voltage; typical values

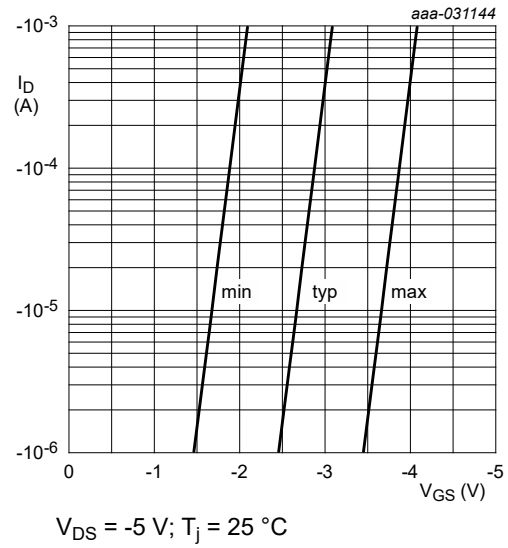


Fig. 7. Sub-threshold drain current as a function of gate-source voltage

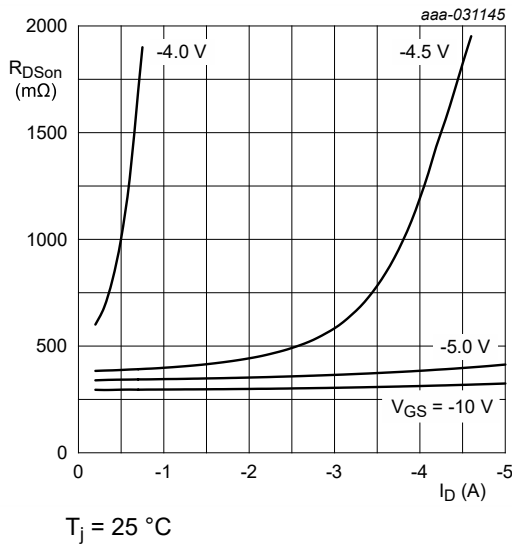


Fig. 8. Drain-source on-state resistance as a function of drain current; typical values

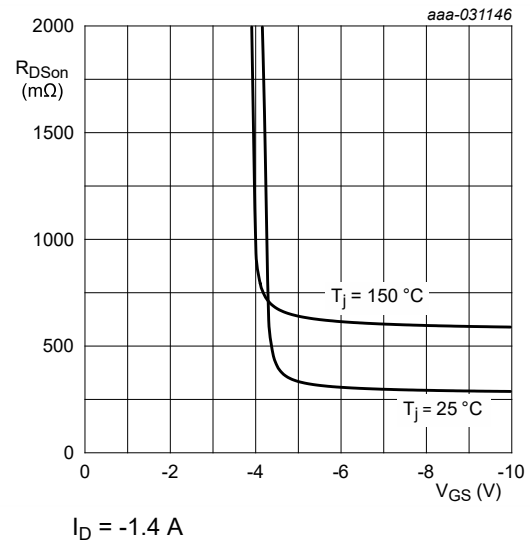


Fig. 9. Drain-source on-state resistance as a function of gate-source voltage; typical values

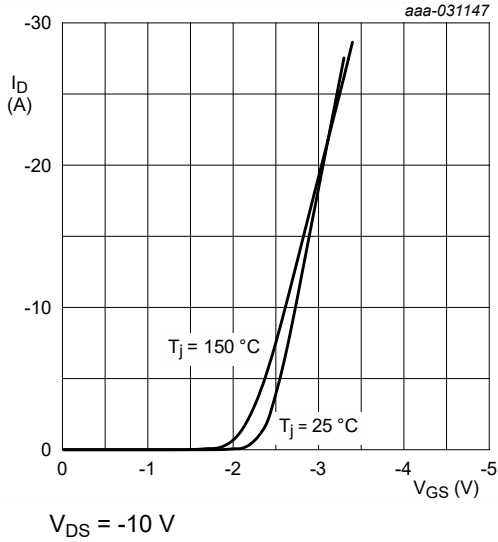
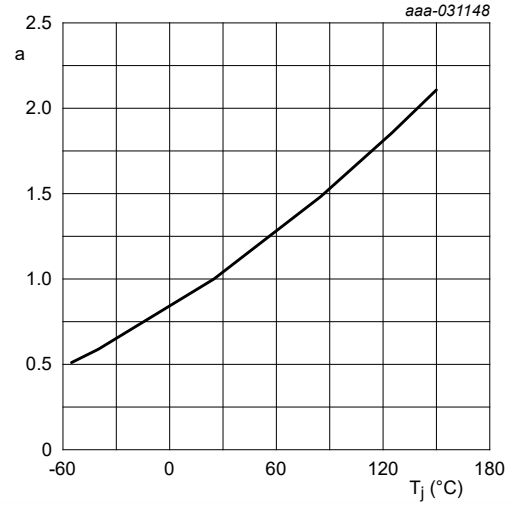


Fig. 10. Transfer characteristics: drain current as a function of gate-source voltage; typical values



$$a = \frac{R_{DSon}}{R_{DSon(25^\circ\text{C})}}$$

Fig. 11. Normalized drain-source on-state resistance as a function of junction temperature; typical values

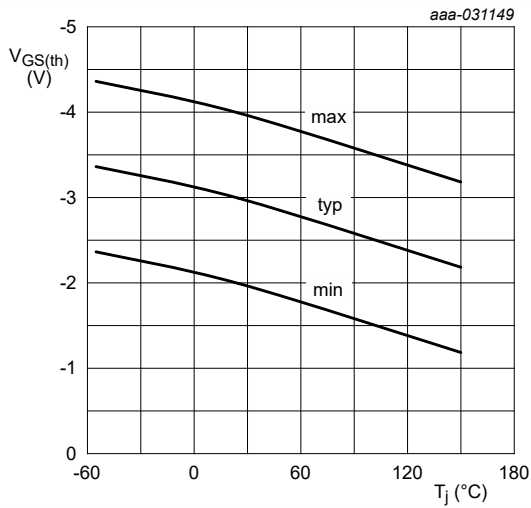


Fig. 12. Gate-source threshold voltage as a function of junction temperature

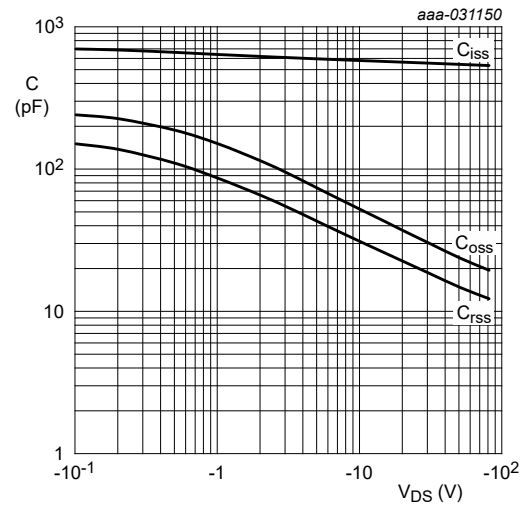
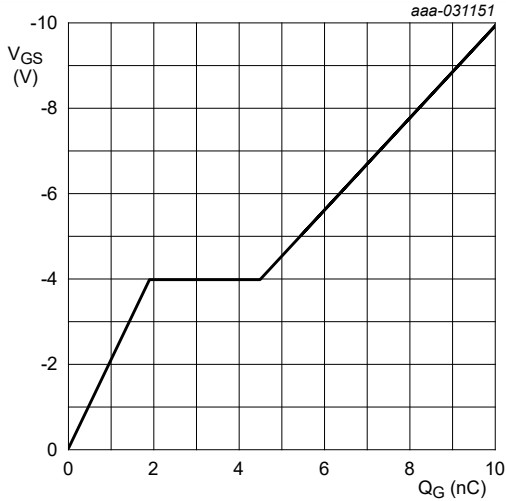


Fig. 13. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values



$I_D = -1.15$ A; $V_{DS} = -50$ V; $T_j = 25$ °C

Fig. 14. Gate-source voltage as a function of gate charge; typical values

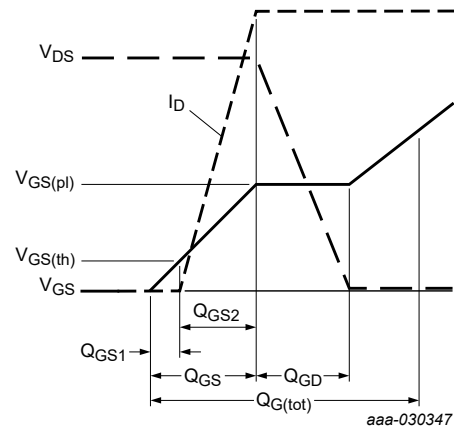
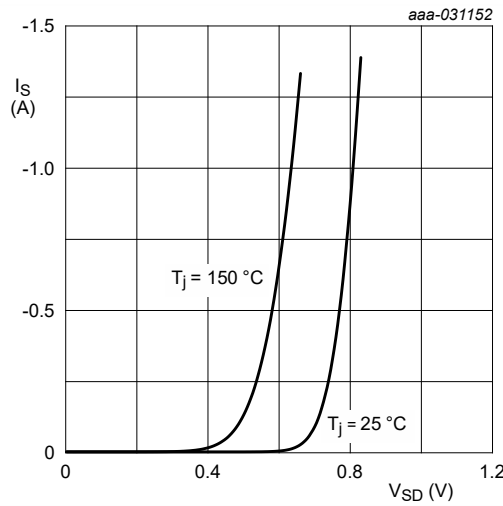


Fig. 15. Gate charge waveform definitions



$V_{GS} = 0$ V

Fig. 16. Source current as a function of source-drain voltage; typical values

11. Test information



Fig. 17. Duty cycle definition

12. Package outline

MLPAK33: plastic thermal enhanced surface mounted package; mini leads; 8 terminals;
pitch 0.65 mm; 3.3 x 3.3 x 0.8 mm body

SOT8002-2

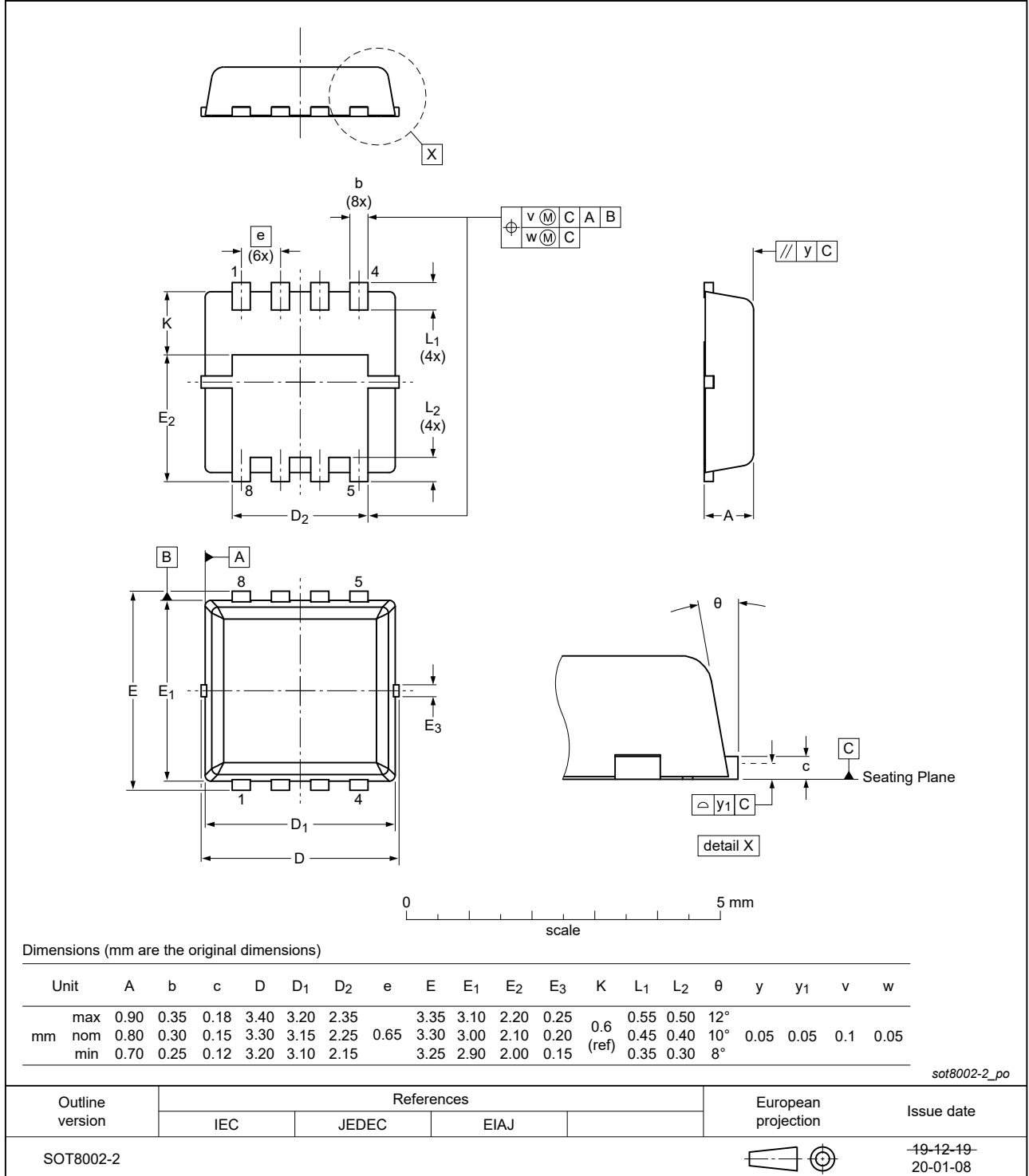


Fig. 18. Package outline MLPAK33 (SOT8002-2)

13. Soldering

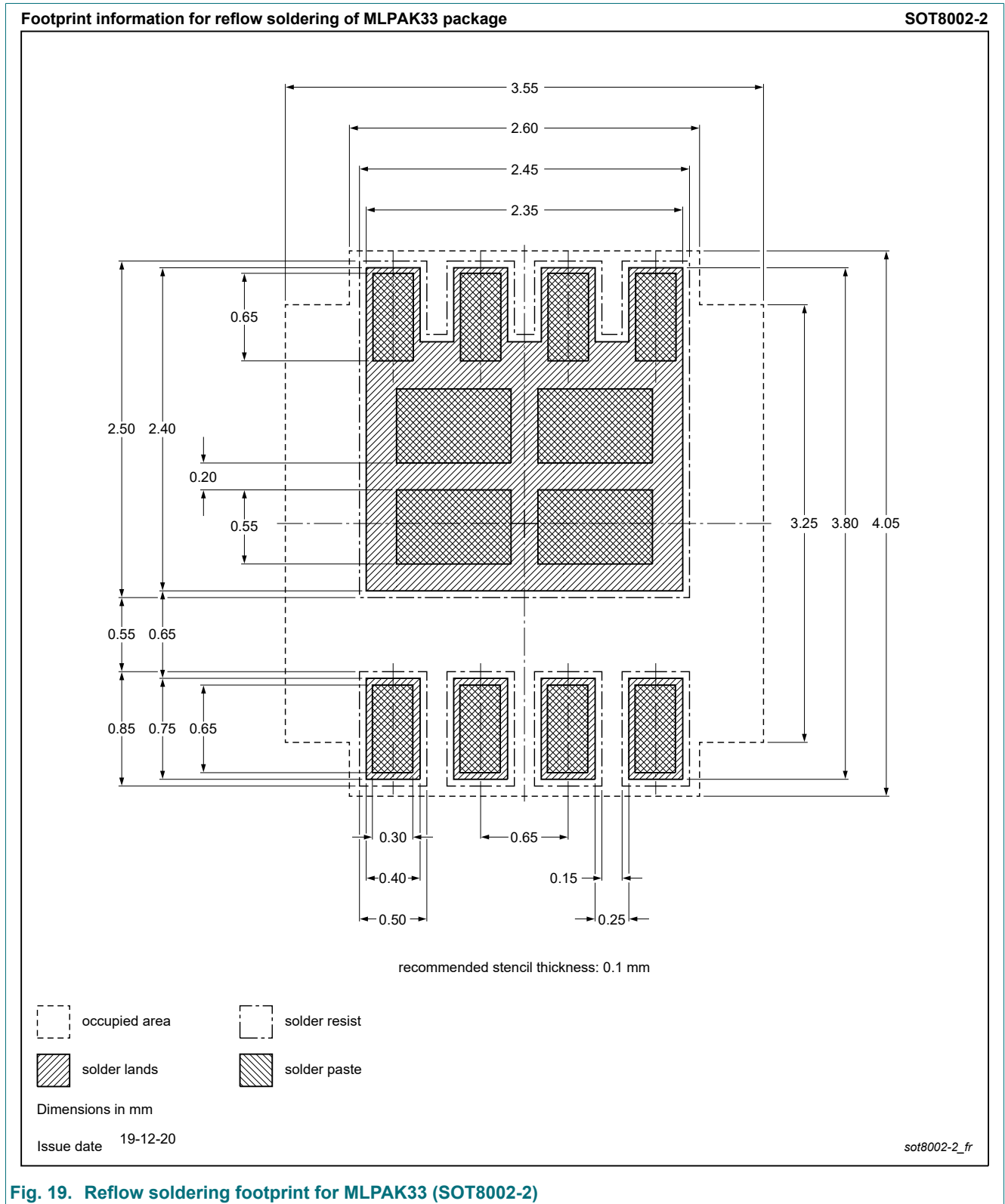


Fig. 19. Reflow soldering footprint for MLPAK33 (SOT8002-2)

14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PXP400-100QS v.1	20200507	Product data sheet	-	-

15. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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- [2] The term 'short data sheet' is explained in section "Definitions".
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